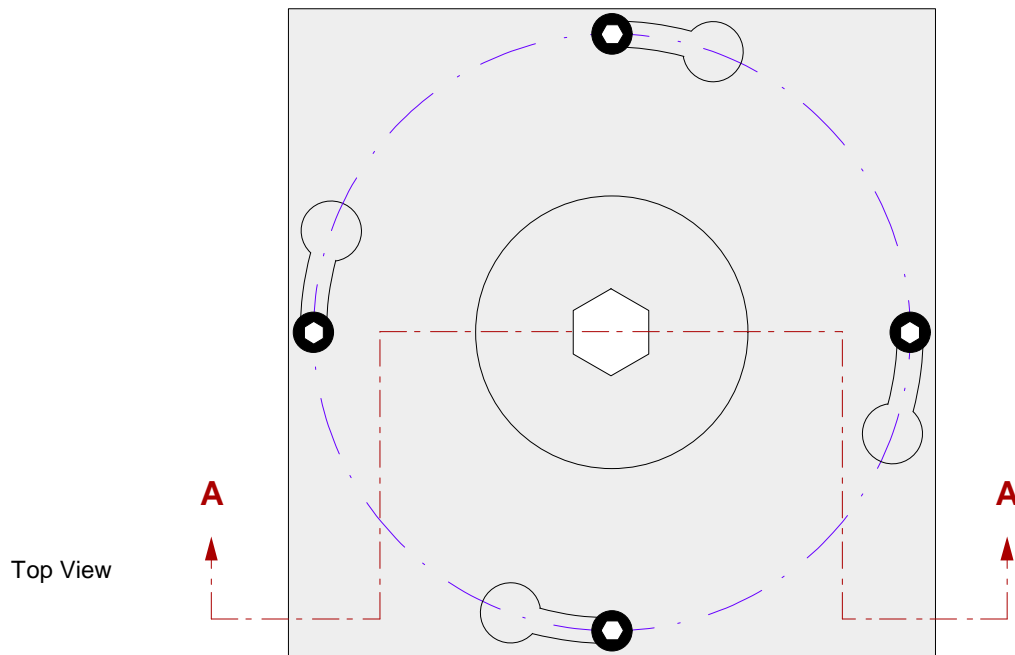


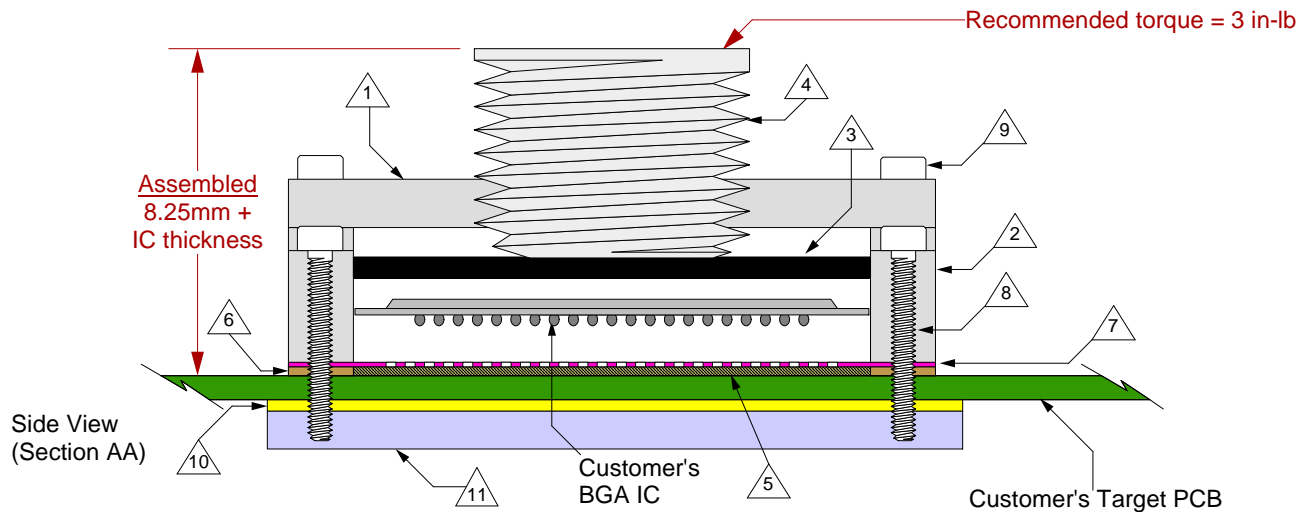
GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid



Top View



Side View
(Section AA)

- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized 6061 Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- △ 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

SG-BGA-7080 Drawing

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11351 Rupp Dr. Suite 400, Burnsville MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

Drawing: M.A. Fedde

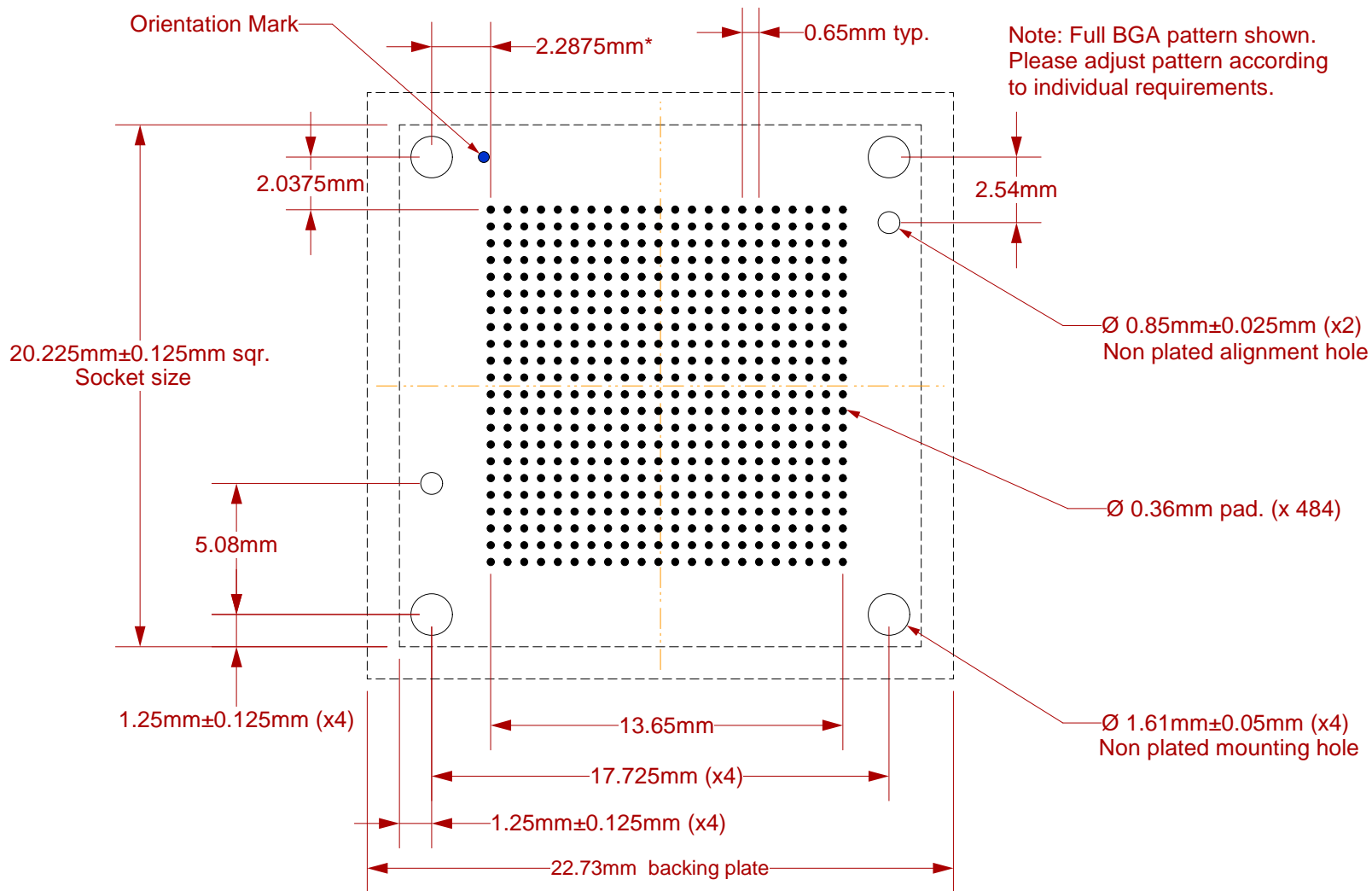
Date: 10/19/06

File: SG-BGA-7080 Dwg

Modified: 7/2/09, AE

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Target PCB Recommendations

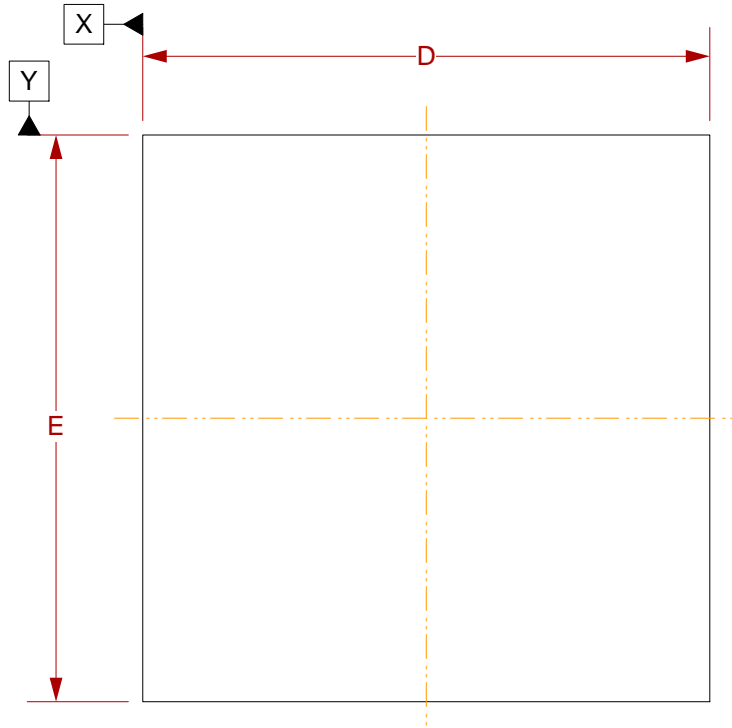
Total thickness: 1.6 mm min.

Plating: Gold or Solder finish

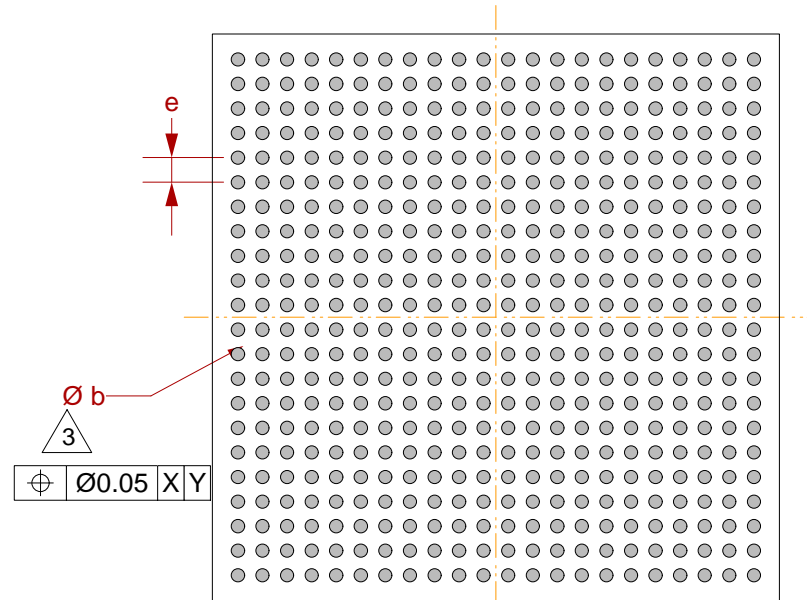
PCB Pad height: Same or higher than solder mask

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

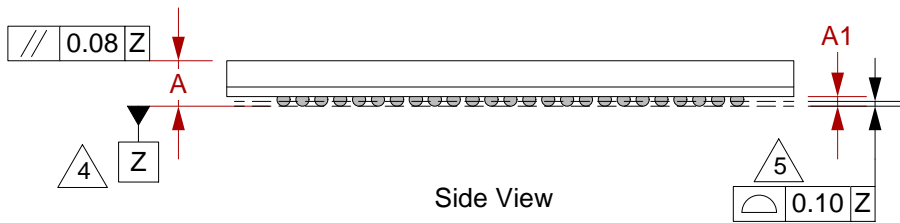
	SG-BGA-7080 Drawing		Status: Released	Scale: 4:1	Rev: B
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400, Burnsville MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com		Drawing: M.A. Fedde		Date: 10/19/06
			File: SG-BGA-7080 Dwg		Modified: 7/2/09, AE



Top View



Bottom View



Side View

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z .
- Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- Parallelism measurement shall exclude any effect of mark on top surface of package.

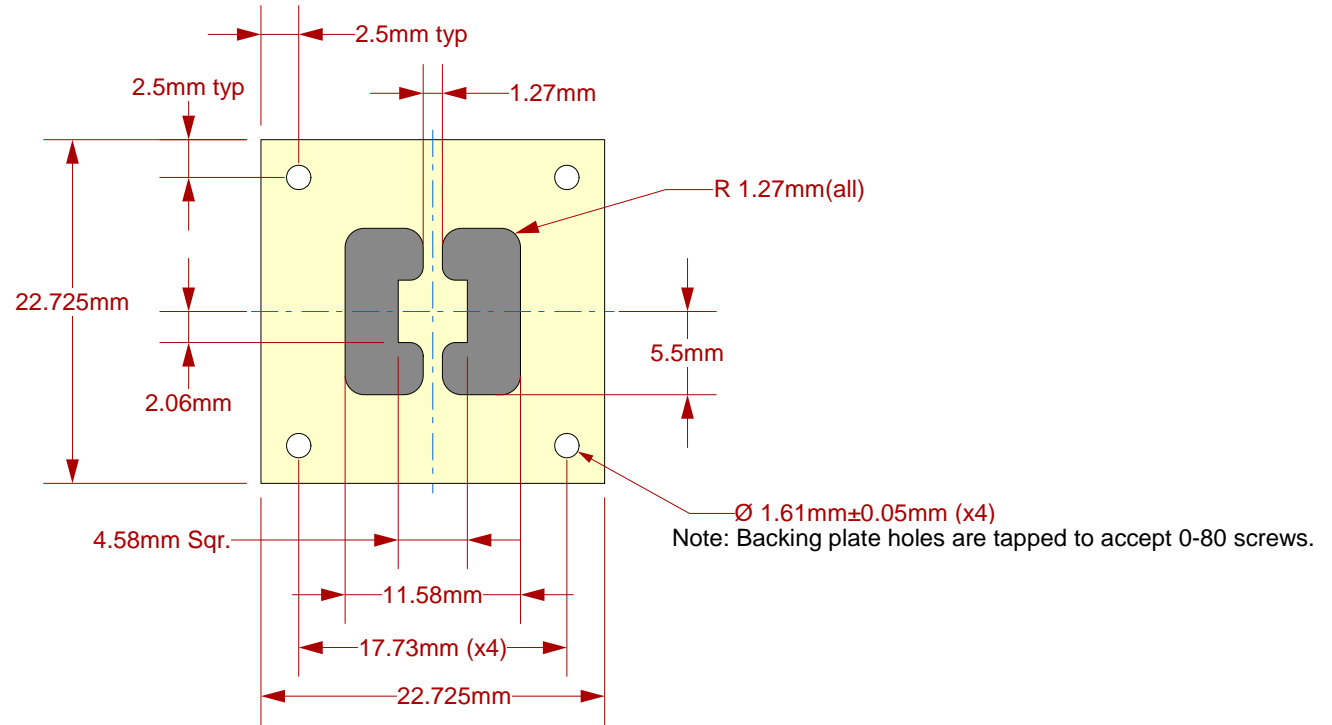
DIM	MIN	MAX
A		1.4
A1	0.21	0.36
b		0.45
D	15.0 BSC	
E	15.0BSC	
e	0.65 BSC	

22 x 22 array

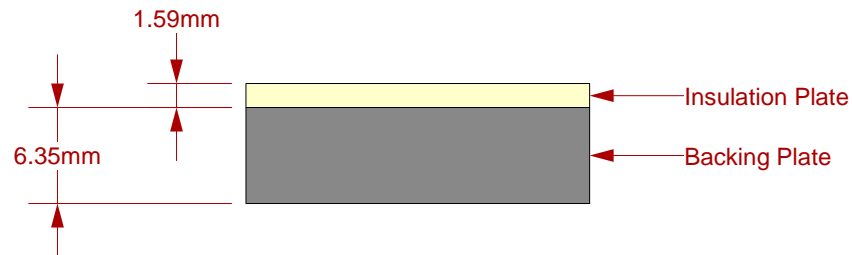
All dimensions are in mm unless stated otherwise

	SG-BGA-7080 Drawing		Status: Released	Scale: -	Rev: B	
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400, Burnsville MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com			Drawing: M.A. Fedde		Date: 10/19/06
				File: SG-BGA-7080 Dwg	Modified: 7/2/09, AE	


Top View



Front View



Description: Insulation Plate and Backing Plate

	SG-BGA-7080 Drawing	Status: Released	Scale: -	Rev: B
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		File: SG-BGA-7080 Dwg	Modified: 7/2/09, AE	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)